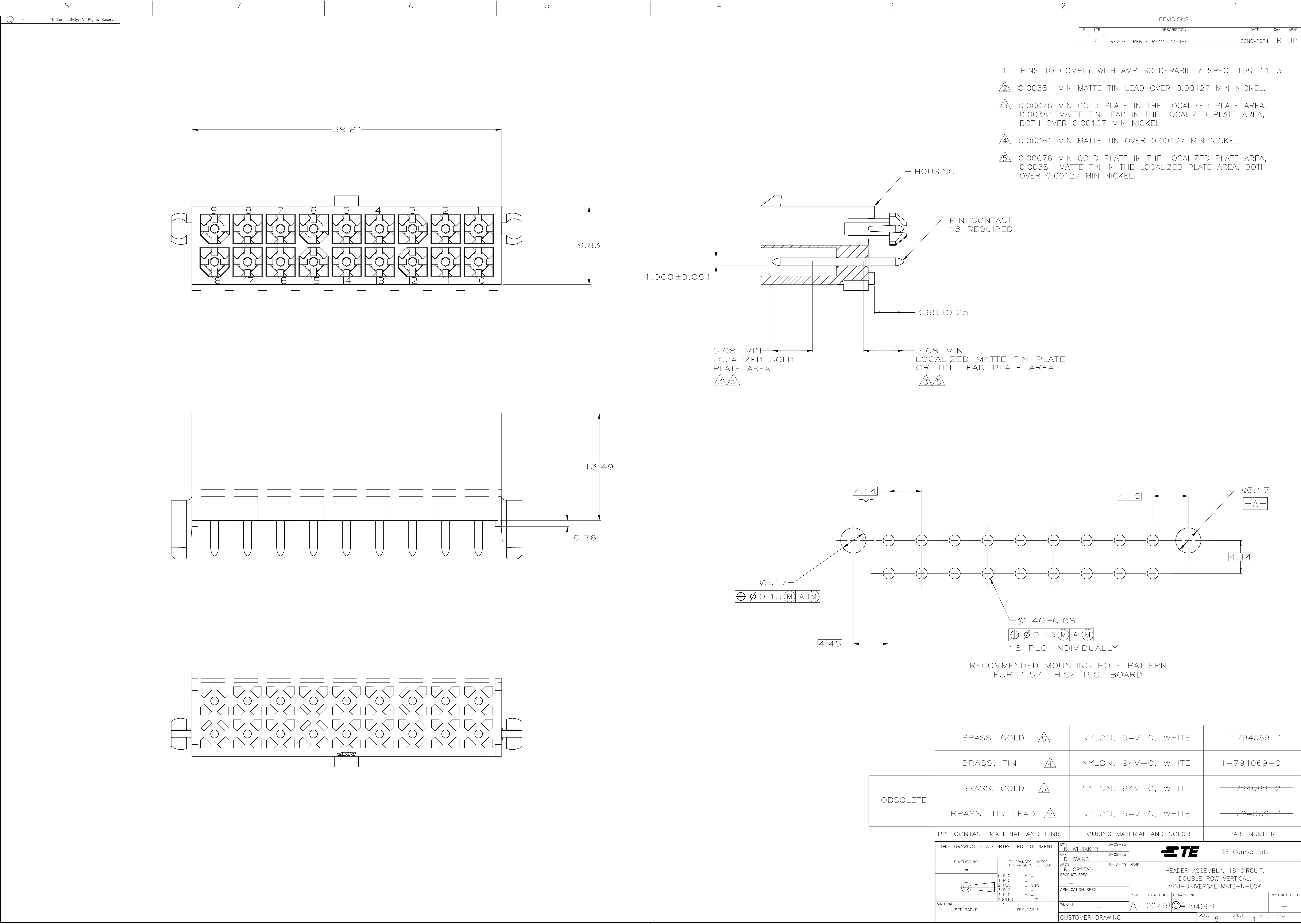
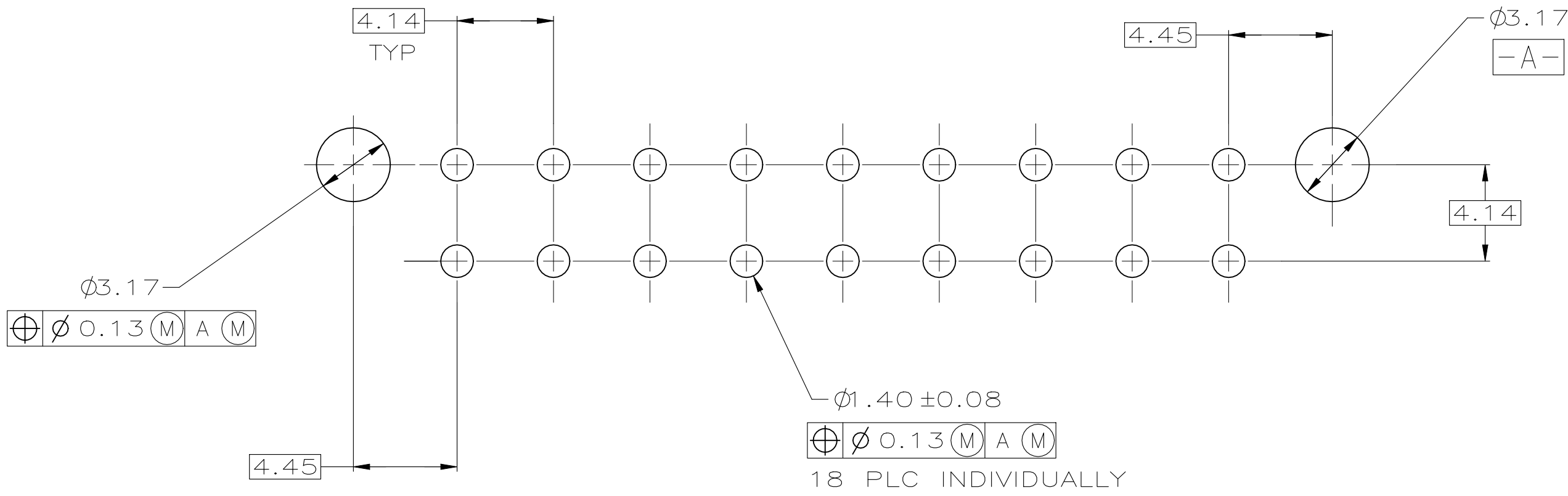
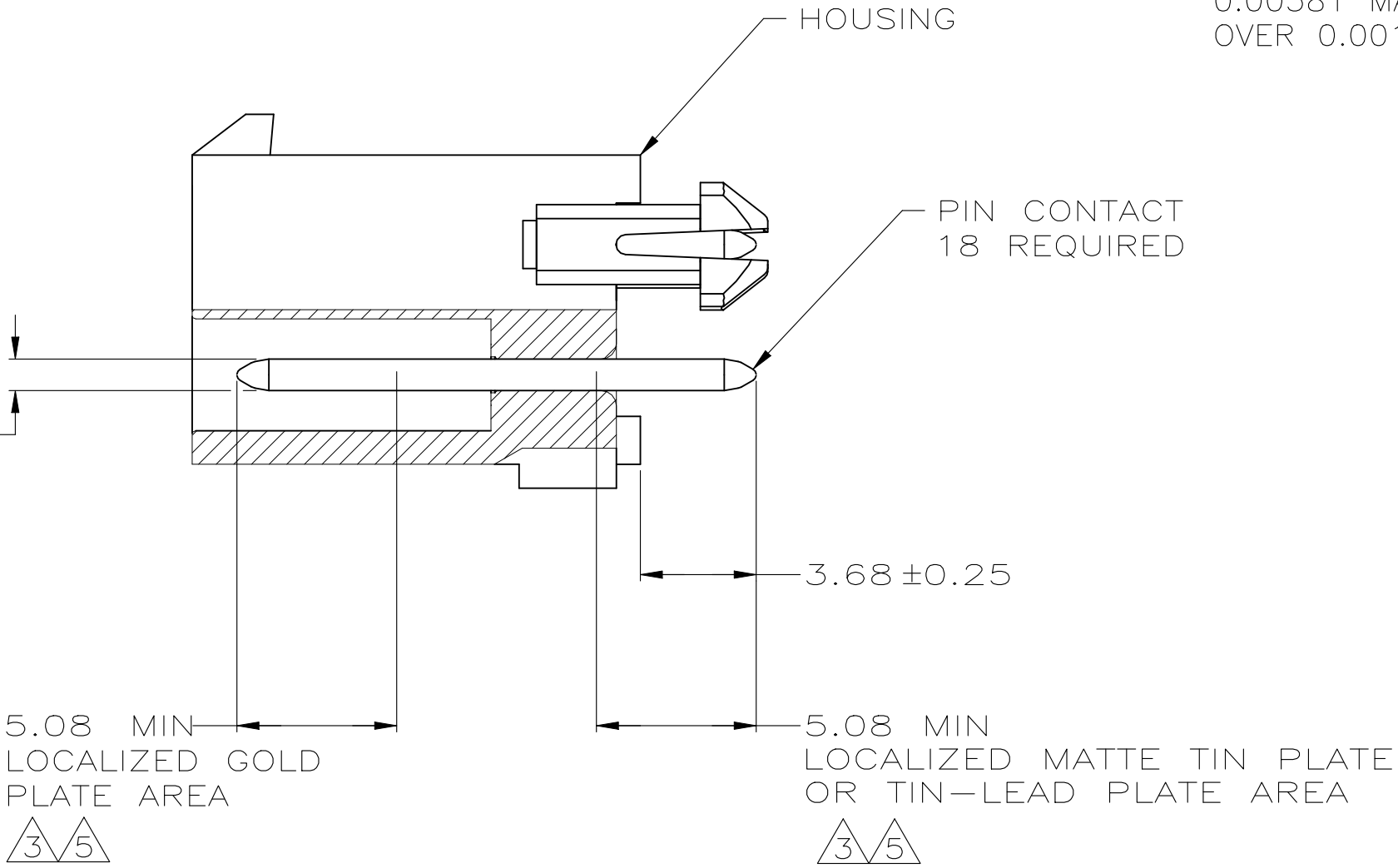




REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
F		REVISED PER ECR-24-226486	20NOV2024	TB	JP

- PINS TO COMPLY WITH AMP SOLDERABILITY SPEC. 108-11-3.
- 0.00381 MIN MATTE TIN LEAD OVER 0.00127 MIN NICKEL.
- 0.00076 MIN GOLD PLATE IN THE LOCALIZED PLATE AREA, 0.00381 MATTE TIN LEAD IN THE LOCALIZED PLATE AREA, BOTH OVER 0.00127 MIN NICKEL.
- 0.00381 MIN MATTE TIN OVER 0.00127 MIN NICKEL.
- 0.00076 MIN GOLD PLATE IN THE LOCALIZED PLATE AREA, 0.00381 MATTE TIN IN THE LOCALIZED PLATE AREA, BOTH OVER 0.00127 MIN NICKEL.



RECOMMENDED MOUNTING HOLE PATTERN
FOR 1.57 THICK P.C. BOARD

OBSOLETE	BRASS, GOLD	NYLON, 94V-0, WHITE	1-794069-1
	BRASS, TIN	NYLON, 94V-0, WHITE	1-794069-0
	BRASS, GOLD	NYLON, 94V-0, WHITE	794069-2
	BRASS, TIN LEAD	NYLON, 94V-0, WHITE	794069-1
PIN CONTACT MATERIAL AND FINISH		HOUSING MATERIAL AND COLOR	PART NUMBER
THIS DRAWING IS A CONTROLLED DOCUMENT.		TE Connectivity	
DIMENSIONS: mm		NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC	
0 PLC ± -		APPLICATION SPEC	
1 PLC ± -		WEIGHT	
2 PLC ± 0.13		A1 00779	
3 PLC ± -		C=794069	
4 PLC ± -		CUSTOMER DRAWING	
ANGLES		SCALE 5:1	
FINISH		SHEET 1 OF 1	
SEE TABLE		REV F	